



景碩科技股份有限公司
Kinsus Interconnect Technology Co.

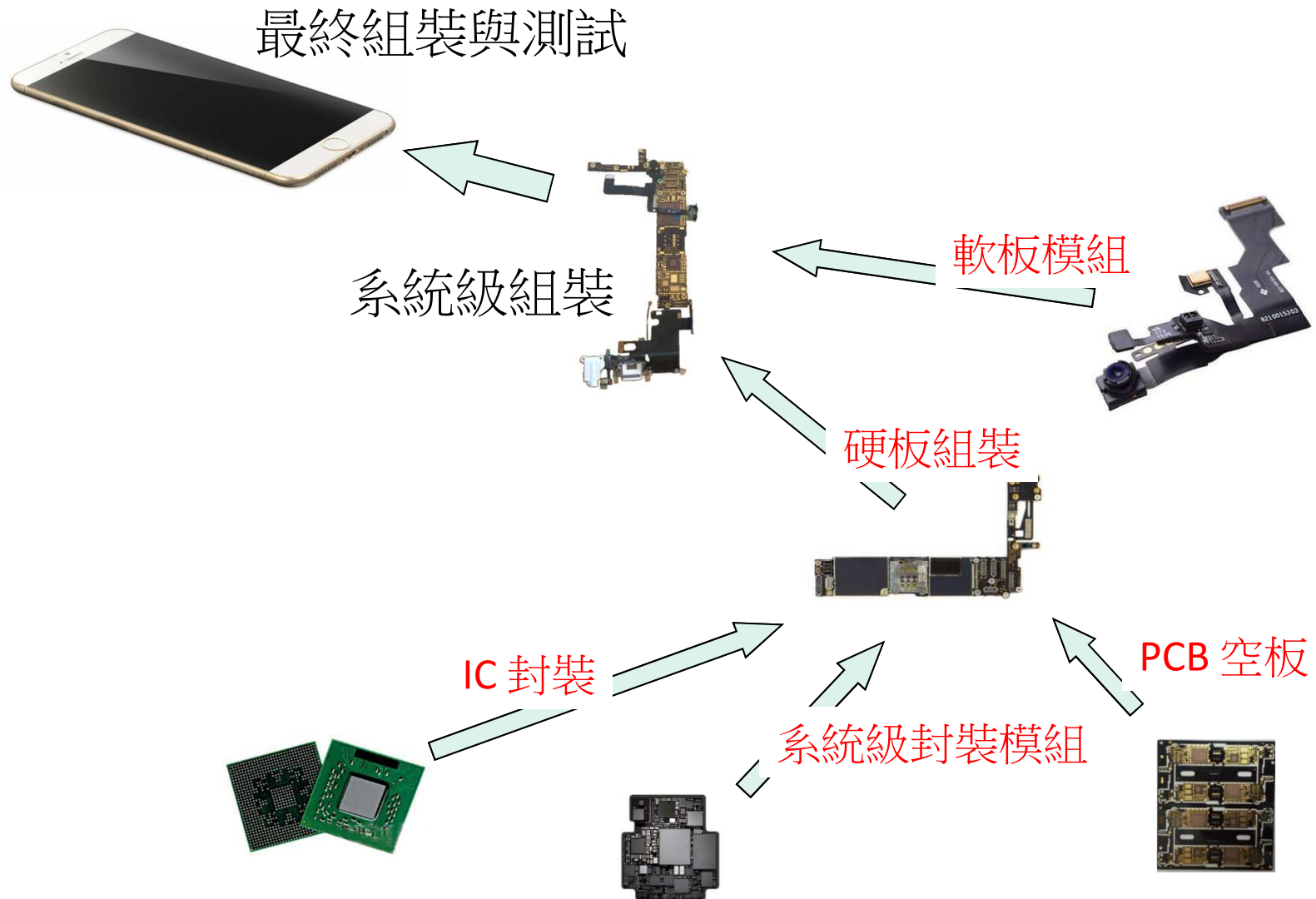
2017 Nov



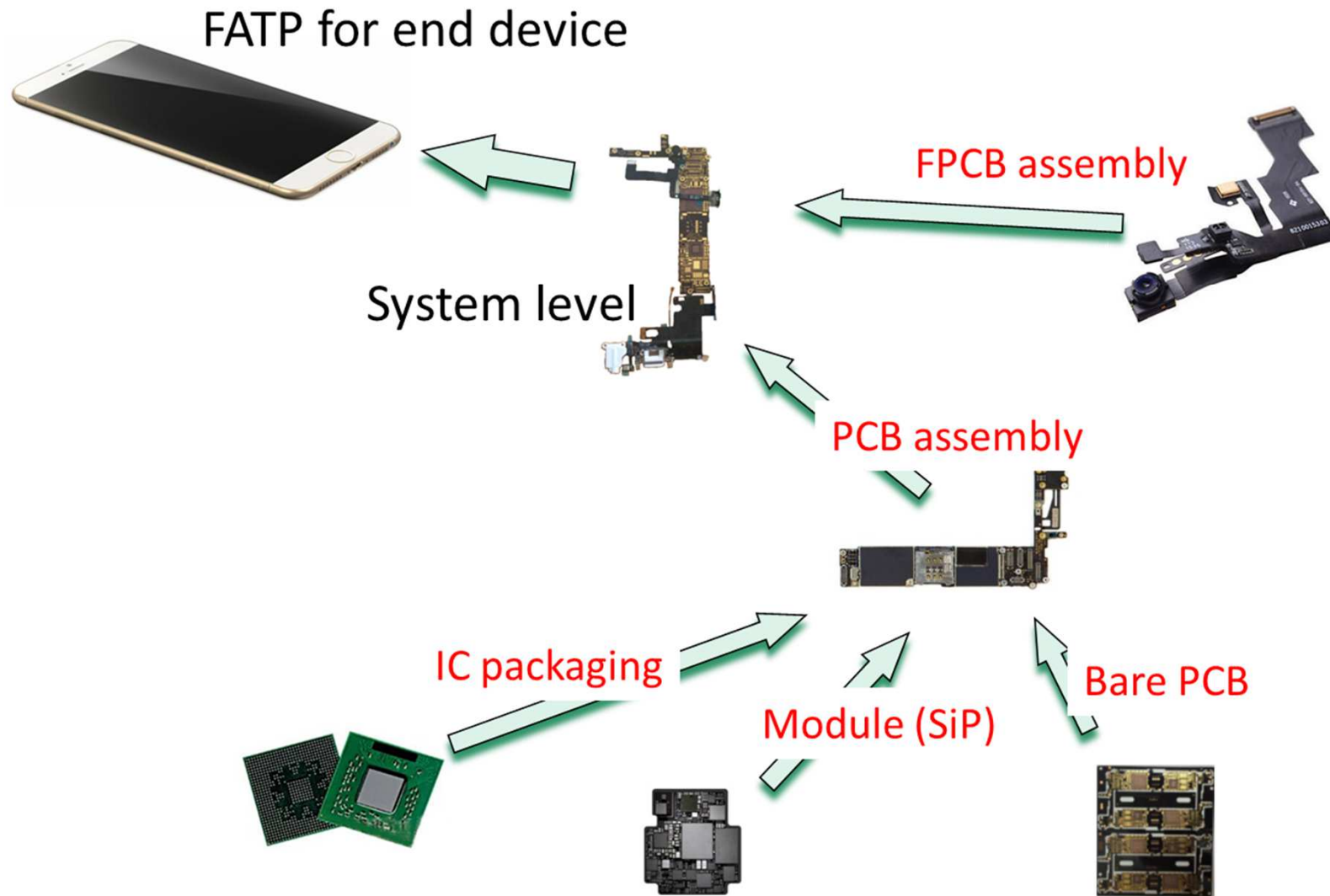
IC 封裝技術

IC Packaging Technology

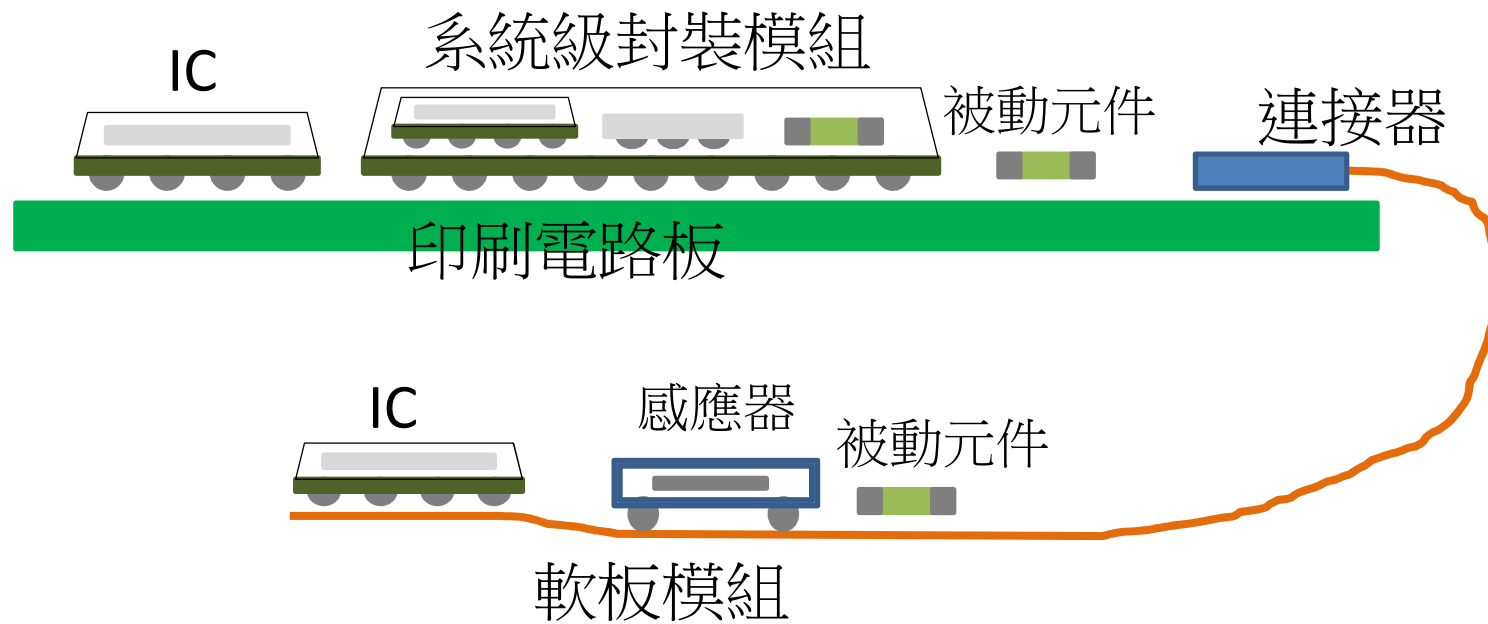
電子產品構裝的各個層次



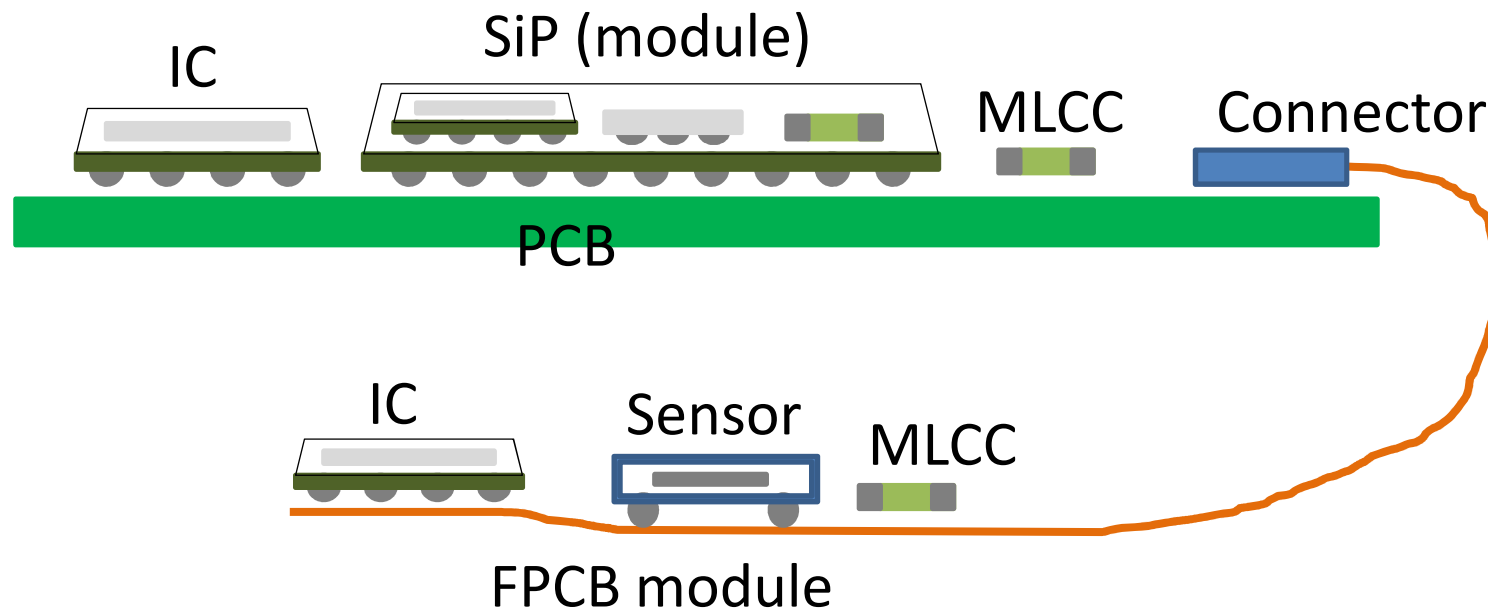
Levels of Assembly



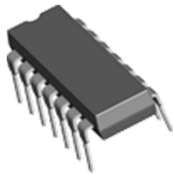
電子產品的組裝結構



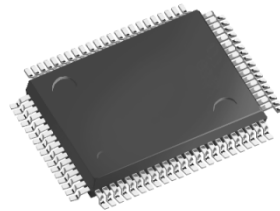
Components in Electronic Device Assembly



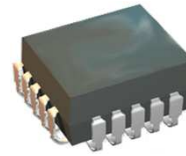
各種形式的 IC 封裝



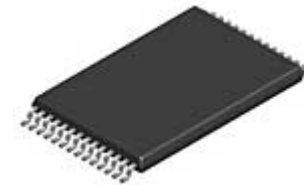
DIP



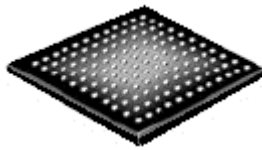
QFP



PLCC



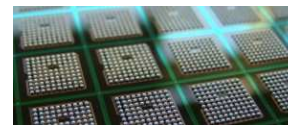
TSOP



PBGA/
Flip-Chip BGA



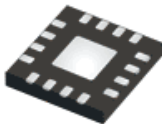
CSP



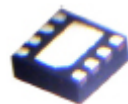
WLP



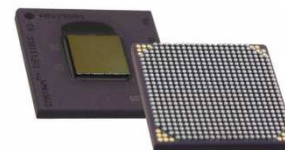
TSV



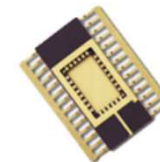
QFN



DFN



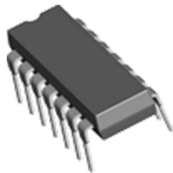
Ceramic BGA



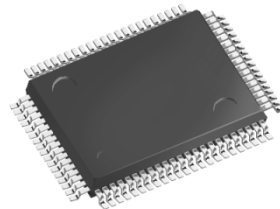
Ceramic chip

市場規模: 215 Billion units in 2015

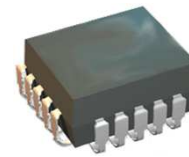
Different types of IC packaging



DIP



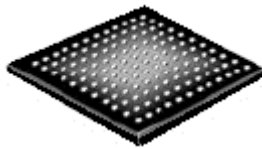
QFP



PLCC



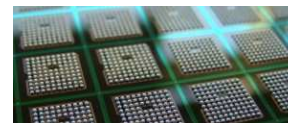
TSOP



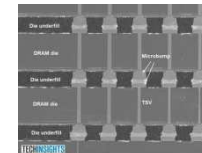
PBGA/
Flip-Chip BGA



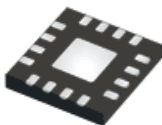
CSP



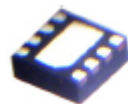
WLP



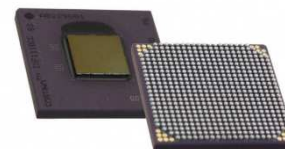
TSV



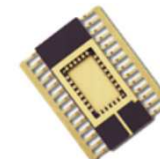
QFN



DFN



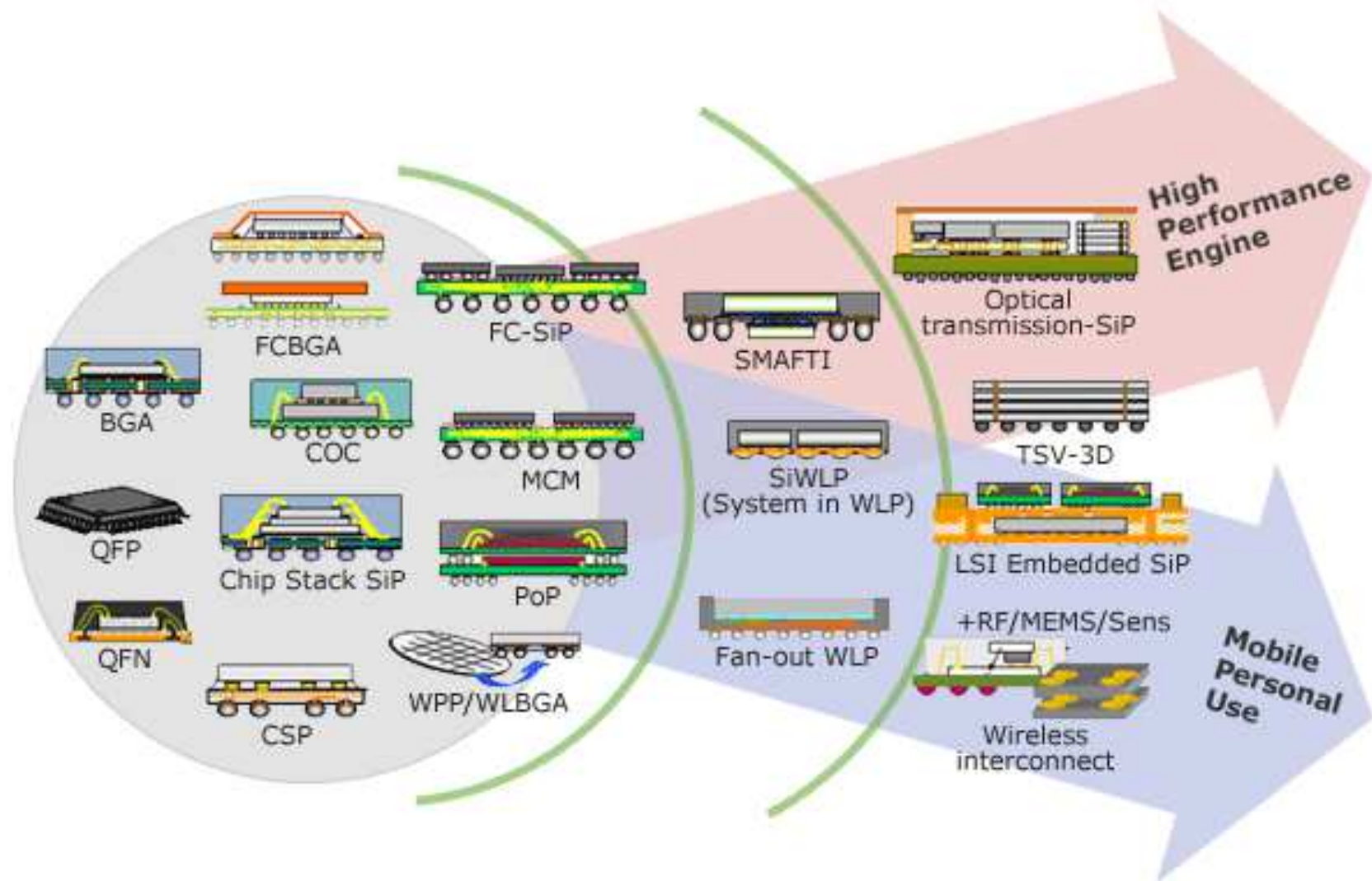
Ceramic BGA



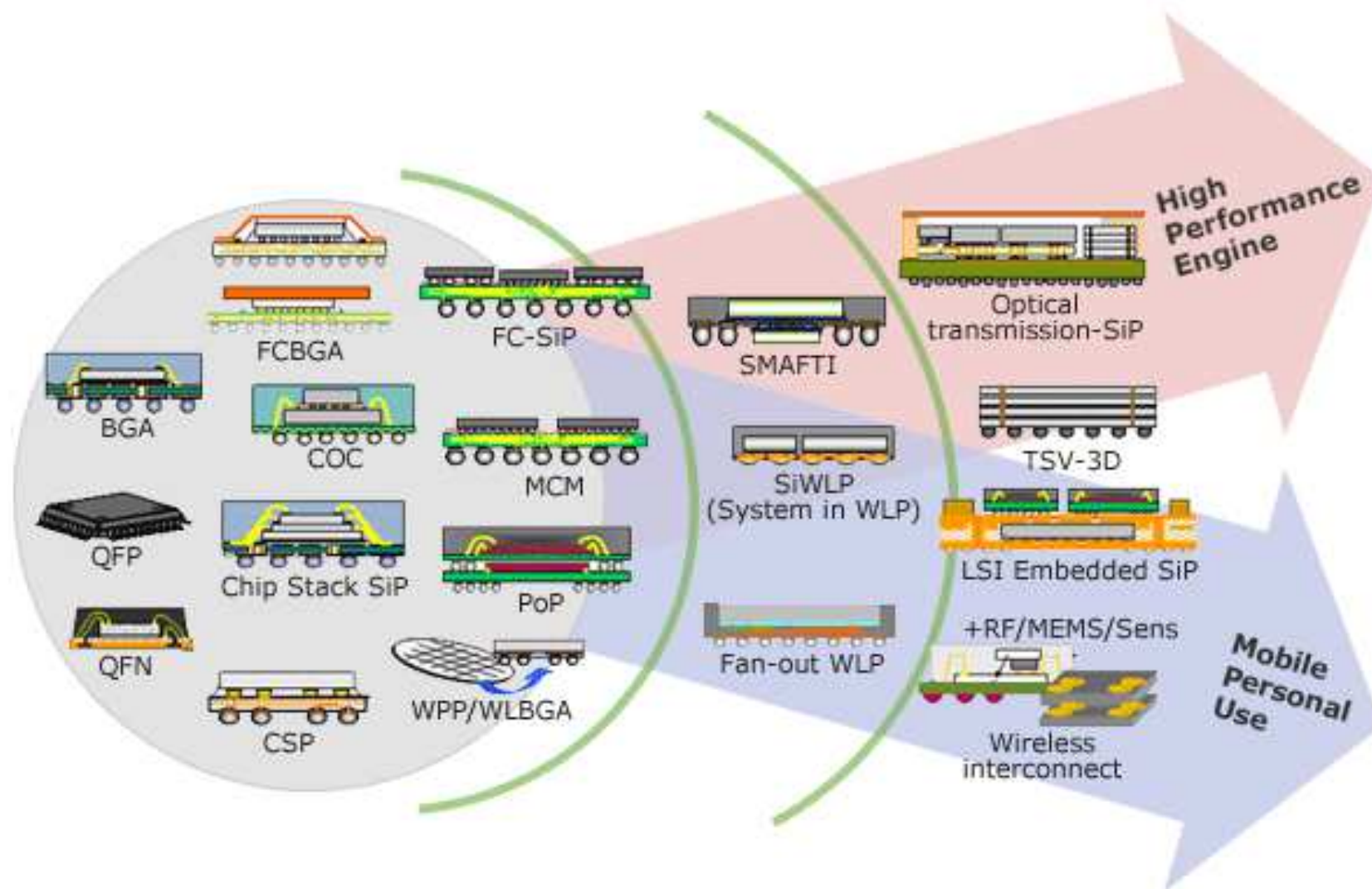
Ceramic chip

Market size : 215 Billion units in 2015

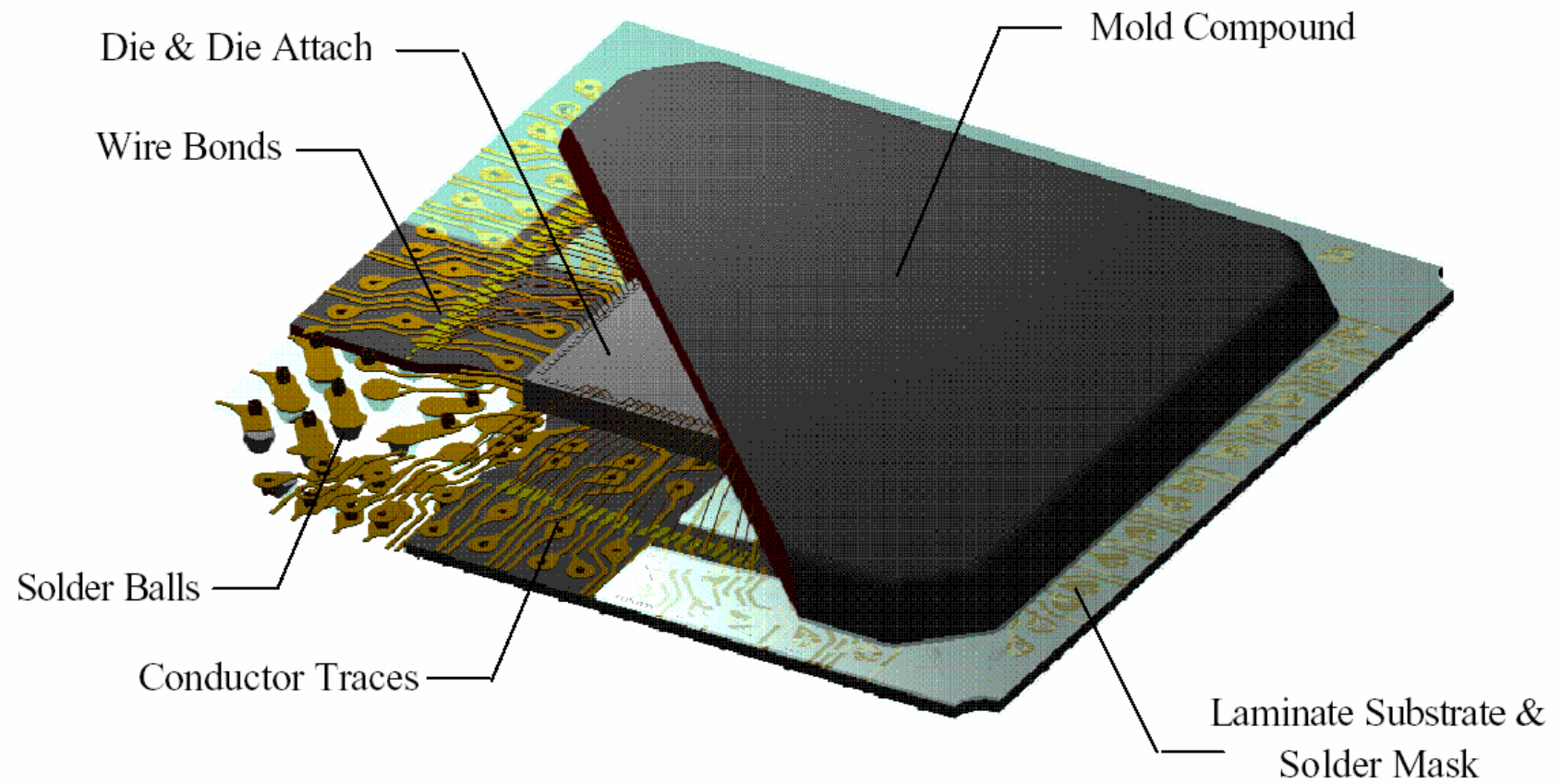
封裝技術走向



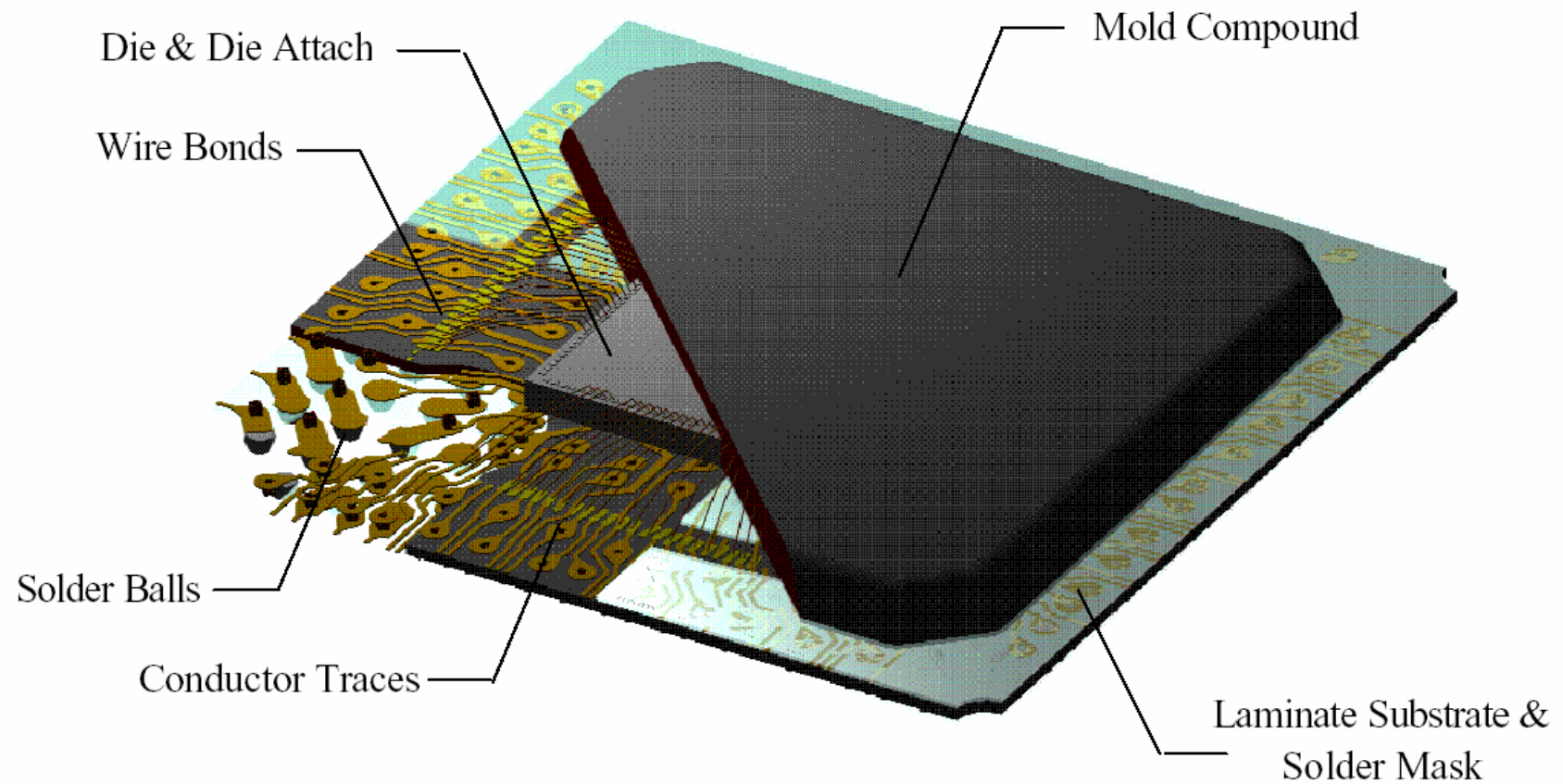
Packaging Technology Roadmap



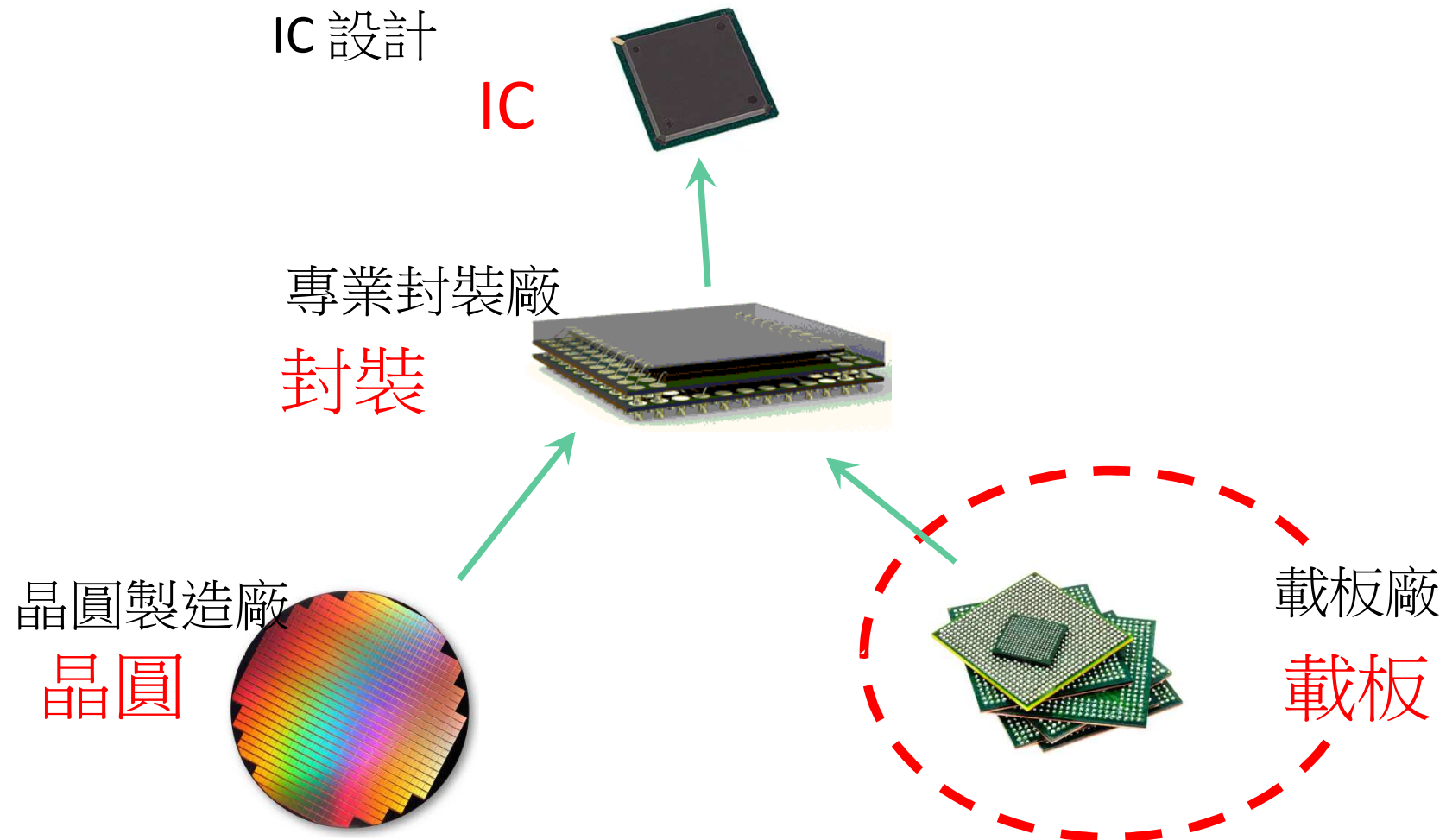
IC 結構



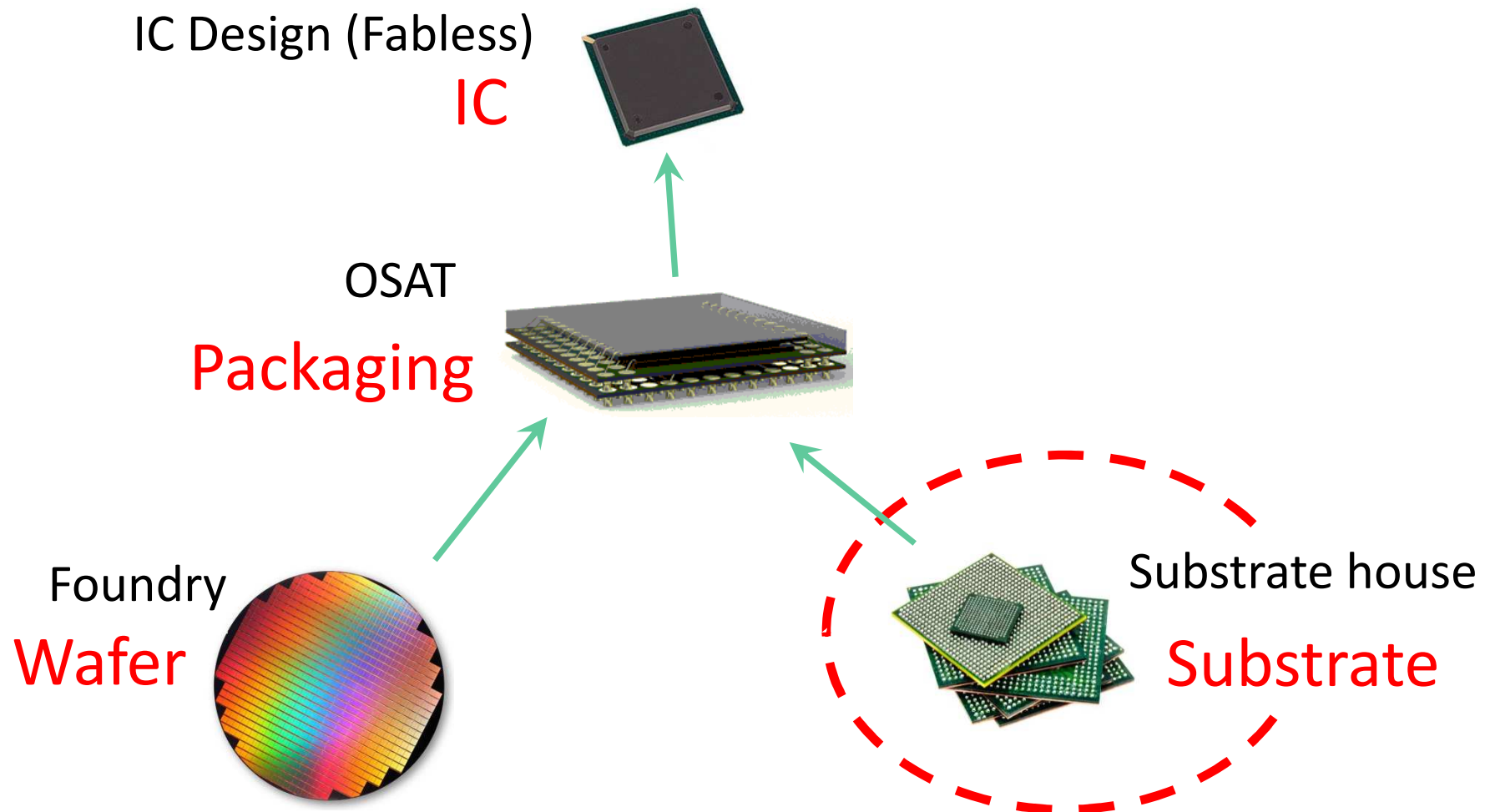
What Substrate Makers do?



IC 半導體上下游供應鏈關係



IC Manufacturing Supply Chain





About Kinsus

基本資料



- 成立 September 2000
上市 November 2004
- 登記資本額 新台幣 44.6 億
- 員工數：4,600 (2017 十一月)
- 廠區：
 - 總部
 - 新屋區 / 桃園市
 - 一廠, 二廠
 - 五廠
 - 美國子公司
 - Santa Clara / California
 - 中國子公司
 - 蘇州

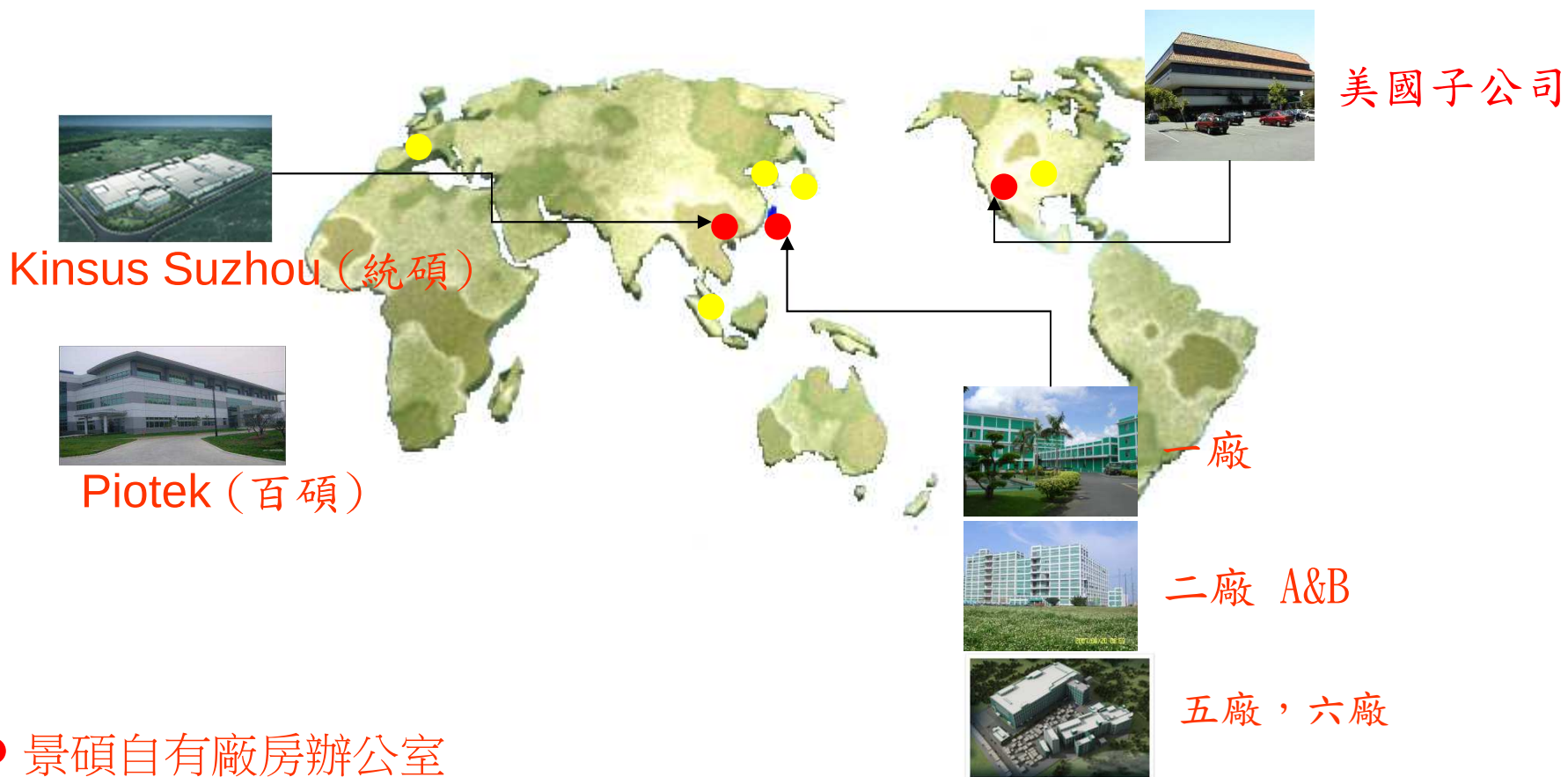
Basic Information



- Established in September 2000
IPO in November 2004
- Capital : US\$ 154 Million (NT\$ 4.46 Billion)
- Headcounts : 4,600 as of Nov 2017
- Campus :

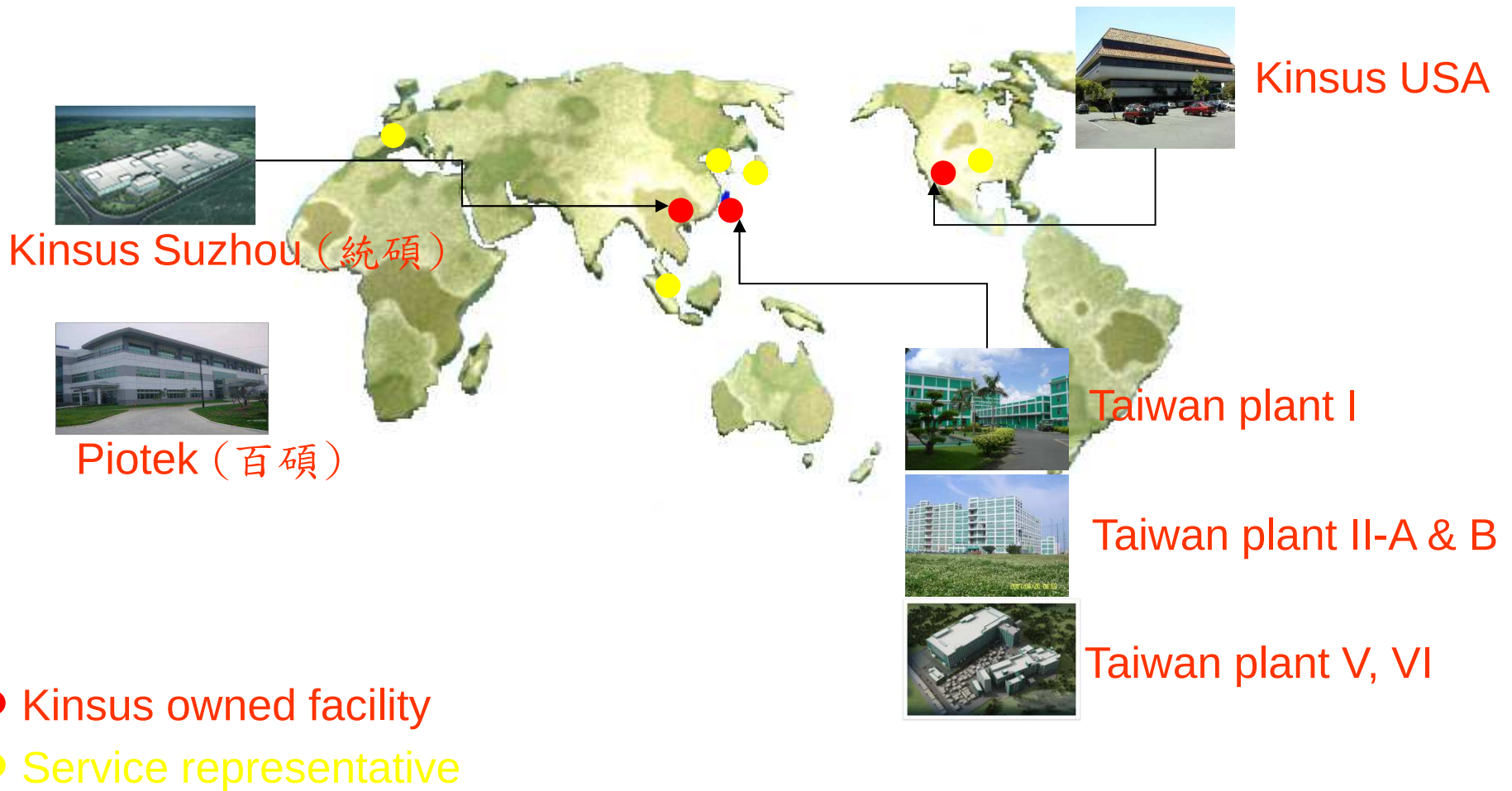
Headquarters	- Xin Wu / Taoyuan
Rigid Substrates BU	- Plant I, Plant II
	- Plant V
Kinsus USA	- Santa Clara / California
Kinsus China	- Suzhou

位置



- 景碩自有廠房辦公室
- 業務代表/代理

Locations



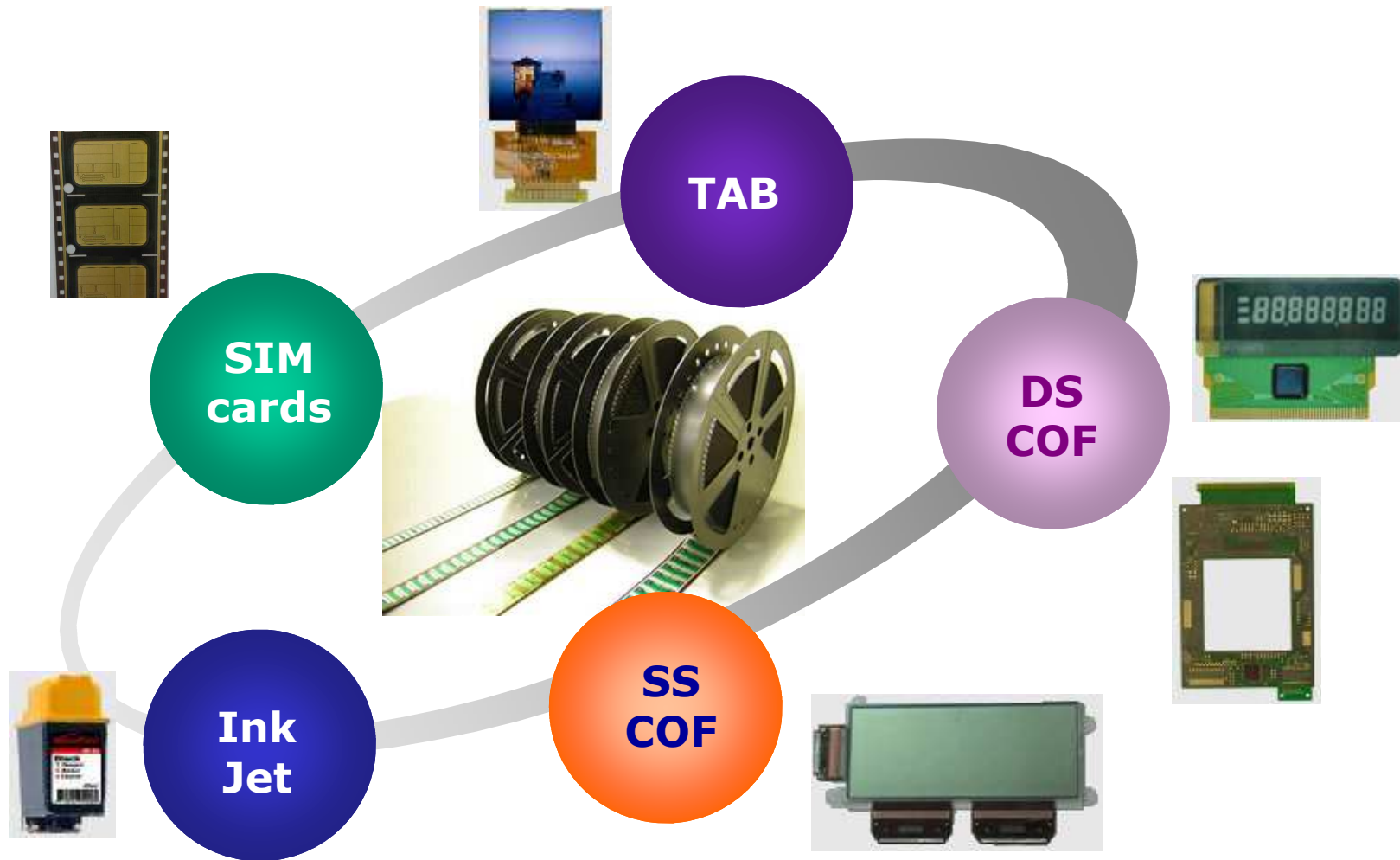
硬質載板產品



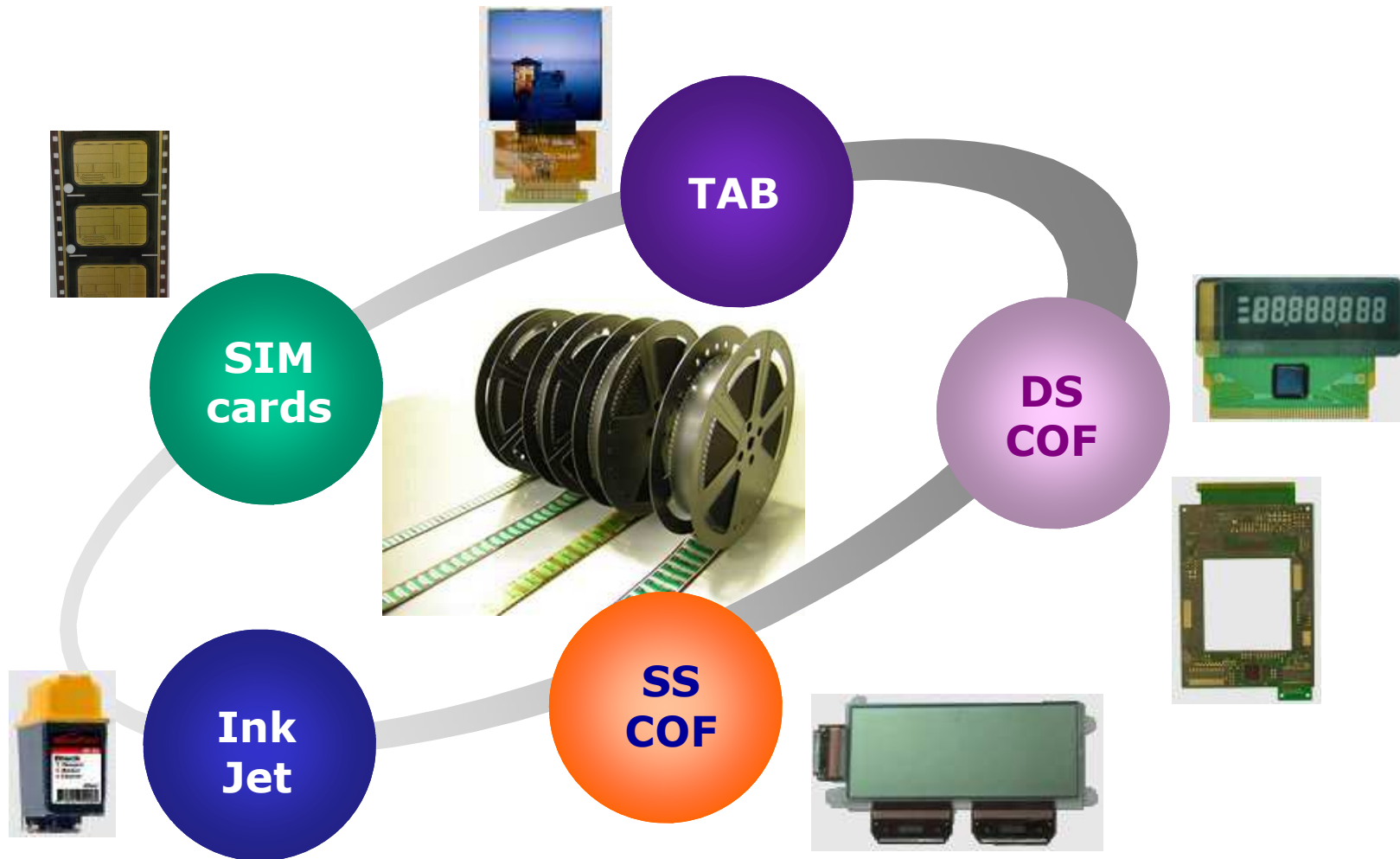
Rigid Substrate Products



軟質載板產品



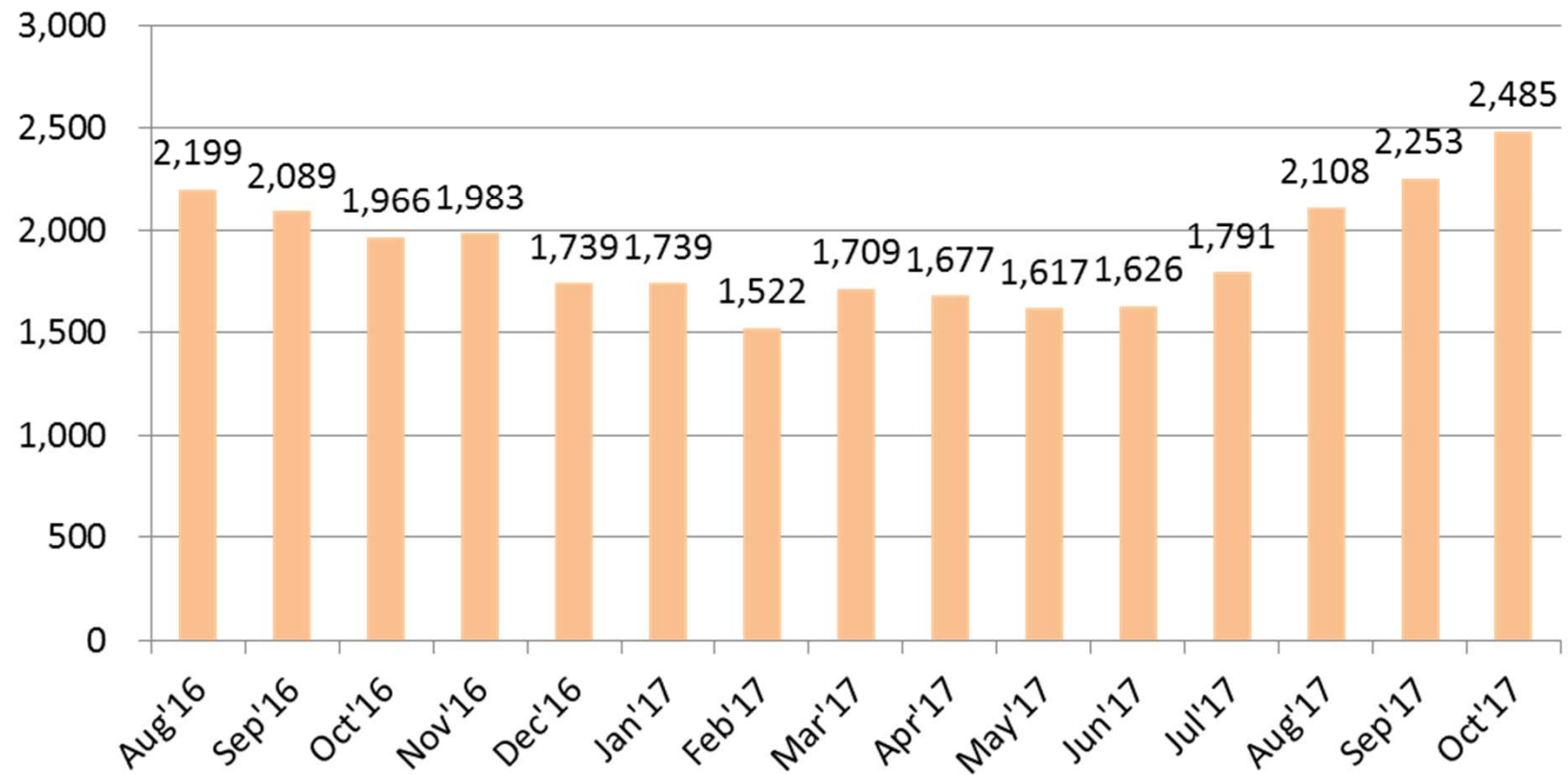
Flexible Substrate Products



每月營業額



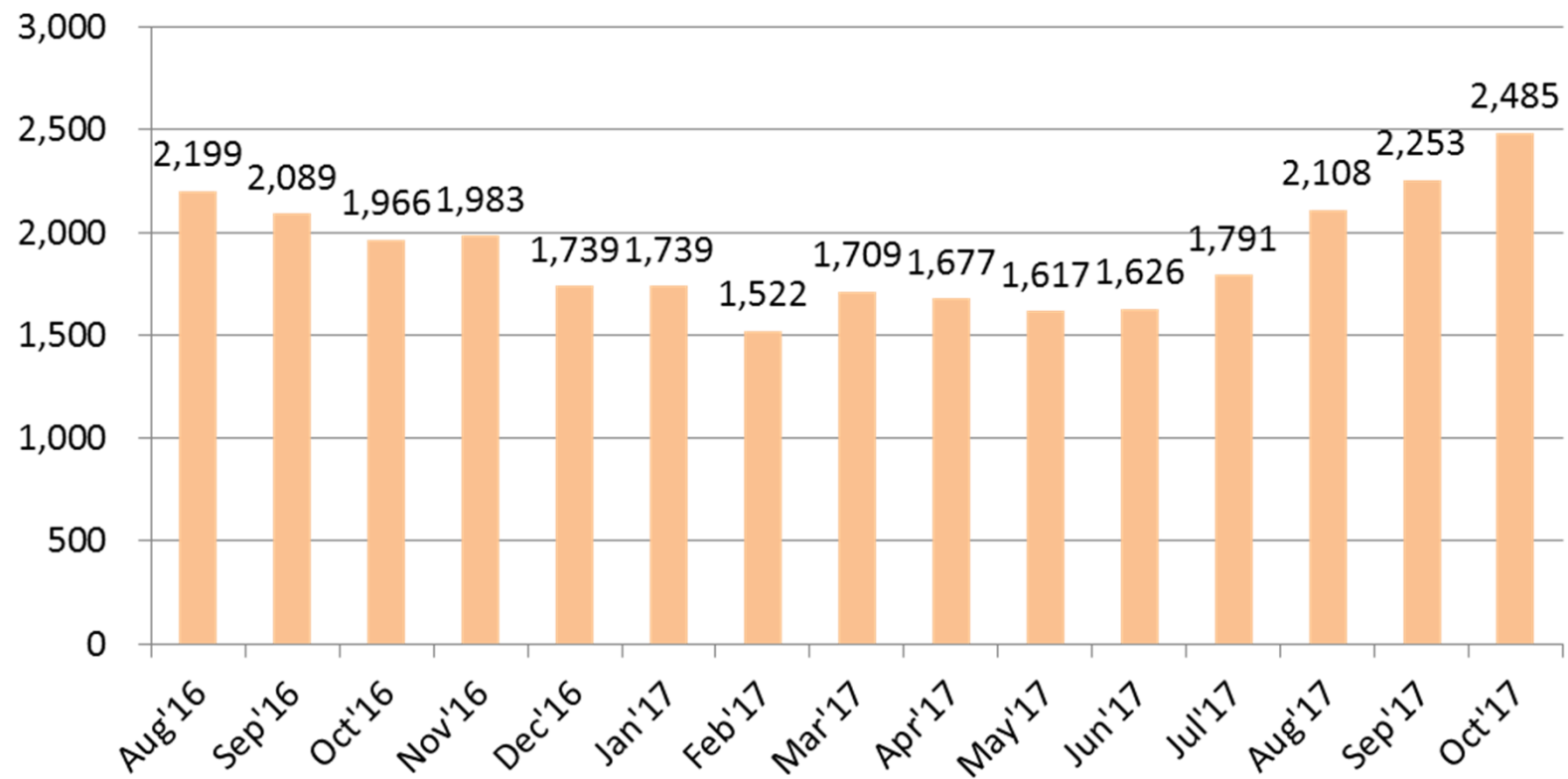
單位：新台幣百萬元



Monthly Revenue



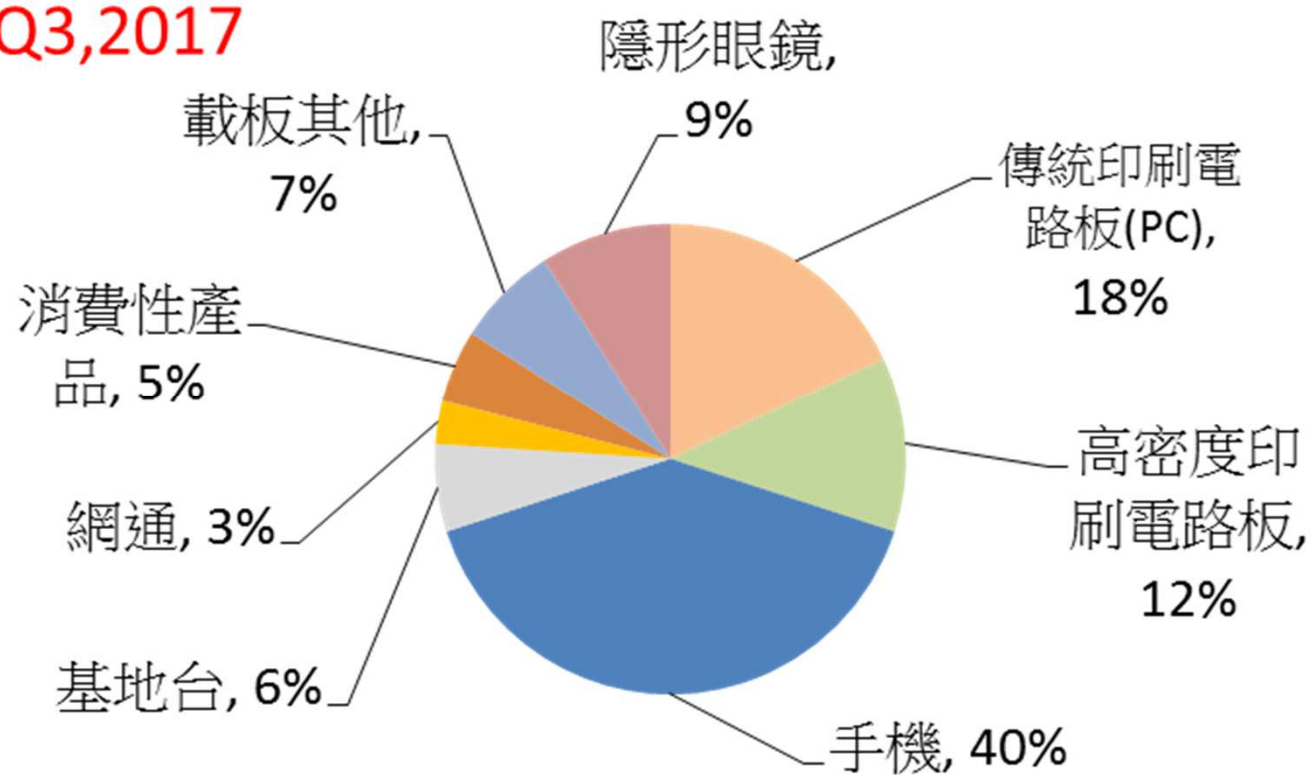
Unit : Million NT\$



營業額分佈



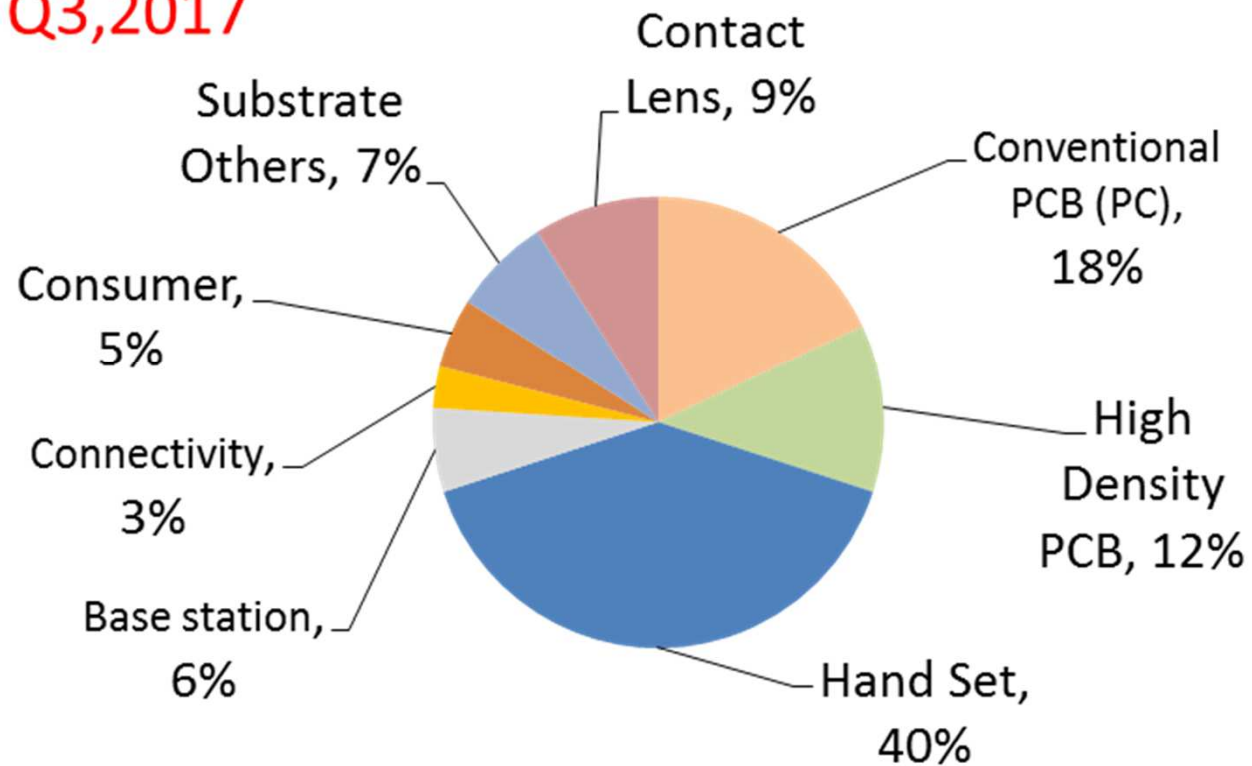
Q3,2017



Revenue - Application



Q3,2017





Thank You!